ABSTRACT

The object of the present invention is to provide a heat resistant thermally conductive material, to which fine powder such as dust, toner, and the like are hard to adhere, and which has good heat radiative properties.

To attain this object, the present invention provides a heat resistant thermally conductive material, being made from an organic-inorganic hybrid material, which is prepared by heating a sol containing a metal or semimetal alkoxide, and an organo · silicon compound, plus a high thermally conductive filler, to gel said sol.

Said organic-inorganic hybrid has excellent mold release characteristics, so that dust, toner, and the like don't easily adhere to the thermally conductive material, and if dust, toner and the like adhere to the thermally conductive material, they are easily removed therefrom. Further, said more highly thermally conductive filler imparts good heat radiative properties to said organic-inorganic hybrid.